



# Product End-of-Life Disassembly Instructions

**Product Category:** Networking Equipment

**Marketing Name / Model**

[List multiple models if applicable.]

J9766A HP 4120 IP Phone

J9766B HP 4120 IP Phone

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm 1 in product	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		3
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Flat blade screw driver	Medium
Phillips screwdriver	# 2
Wire cutter	Medium
Phillips screwdriver	# 1

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Using phillips screwdriver #2, remove 5 screws at rear of case. 4 screws are at corners and 5<sup>th</sup> is near middle. (Additional 2 pairs of screw for brackets that support angled base do not need to be removed, but can be removed for completeness of reycling.)
2. Using flat-blade screwdriver, pry case front out of case rear. There are 7 retaining catches, one at top, 2 at bottom and 2 at each side.
3. Disconnect or cut 4 cables connected from case bottom to PCAs.
4. Case rear: Microphone can be pulled out by hand. Handset connectors are secured by 2 clips each which can be pushed back with a flat-blade screwdriver. Speaker cover is difficult to remove.
5. Unplug or cut two cables connecting small and medium size PCAs,
6. Unplug or cut one remaining cable to the large PCA under the other 2 PCAs.
7. Use phillips #1 screwdriver to remove 3 screws from small PCA, and disposition small PCA.
8. Use phillips #1 and #2 screwdrivers to remove 2 screws from medium-size PCA.
9. Unplug medium-size PCA form connectors underneath it, and disposition PCA.
10. Disconnect flat display cable from the large remaining PCA by lifting connector retaining clamp at connector.
11. Using phillips #2 screwdriver, remove 10 screws holding largest PCA, and disposition PCA.
12. Remove 2 rubberized keypad supports.
13. Separate all plastic key parts from rubber supports.
14. Display is secured with adhesive tape around edges. Use flat blade screwdriver to pry display out of case.
15. Use phillips #2 screwdriver to remove one remaining screw holding very small PCA.
16. Handset shells are connected with 10 clips and are difficult to disassemble. Handsets contain no materials requiring selective treatment.
- 17.
- 18.
- 19.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).